Special Issue

Electronic Packaging Materials and Technology Applications

Message from the Guest Editors

In light of the escalating demand for advanced electronic devices, the domains of 2.5D/3DIC packaging, power device packaging, and low-temperature application packaging have acquired significant attention. These packaging techniques find application in cutting-edge electronic products such as smart devices, electric vehicles, solar energy converters, 5G equipment, and flexible electronics. Consequently, the development of packaging materials, processes, and applications holds critical importance in addressing human well-being, energy concerns, advanced communication equipment, and biomedical products. We hereby introduce a Special Issue on "Electronic Packaging Materials and Technology Applications". Our collection contains a wide spectrum of research issues, including electronic packaging, solder joint, twinned Cu film, transient liquid phase bonding, metal-metal direct bonding, 3DIC interconnection, power device packaging, low-temperature alloys, materials characterization, and reliability issues— all relevant to advanced packaging technology. We eagerly anticipate the support and contributions of experts in these fields.

Guest Editors

Dr. Yu-An Shen

Department of Materials Science and Engineering, Feng Chia University, Taichung 407, Taiwan

Prof. Dr. Chih-Ming Chen

Department of Chemical Engineering, National Chung Hsing University, Taichung, Taiwan

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Materials
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
materials@mdpi.com

mdpi.com/journal/materials

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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Editor-in-Chief

Prof. Dr. Maryam Tabrizian
1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada
2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

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